



Material Content Data Sheet



Sales Product Name		BTS721L1		Issued		29. August 2013		
MA#		MA000946798						
Package		PG-DSO-20-59		Weight*		499.85 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	14.030	2.81	2.81	28068	28068
leadframe	non noble metal	zinc	7440-66-6	0.169	0.03		339	
	inorganic material	phosphorus	7723-14-0	0.042	0.01		85	
	non noble metal	iron	7439-89-6	3.388	0.68		6779	
	non noble metal	copper	7440-50-8	137.580	27.52	28.24	275240	282443
wire	noble metal	gold	7440-57-5	1.405	0.28	0.28	2812	2812
encapsulation	organic material	carbon black	1333-86-4	0.668	0.13		1335	
	plastics	epoxy resin	-	30.705	6.14		61429	
	inorganic material	silicondioxide	60676-86-0	302.380	60.50	66.77	604938	667702
leadfinish	non noble metal	tin	7440-31-5	2.746	0.55	0.55	5493	5493
plating	noble metal	silver	7440-22-4	3.476	0.70	0.70	6955	6955
glue	plastics	epoxy resin	-	0.571	0.11		1142	
	noble metal	silver	7440-22-4	2.692	0.54	0.65	5385	6527
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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